

# Fracture Behaviour of Engineered Fiber/Matrix Interfaces in Fibrous Tungsten/Tungsten Composites

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## Background

Tungsten— armour material for the plasma-facing component of fusion reactors

### 😊 Advantages

- ✓ high melting point
- ✓ high thermal shock resistance
- ✓ high erosion resistance



Tungsten monoblock

### 😢 Drawbacks

- ✗ inherent brittleness
- ✗ embrittlement      { neutron radiation  
                          recrystallization

Severe brittleness limits its engineering application!

Therefore an **effective toughening technique** is required to increase the toughness to an acceptable level.

### Metallurgical approaches

- Oxide Particle Dispersion ( $\text{La}_2\text{O}_3$ ),
- Doping (K),
- Mechanical alloying (Re)
- Severe Plastic Deformation

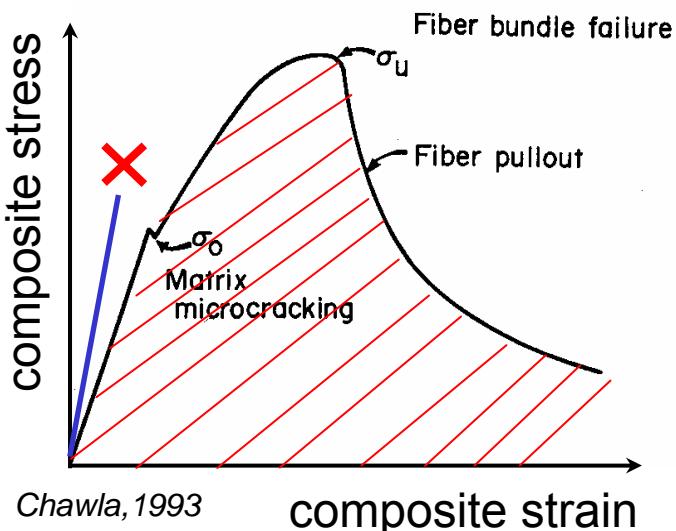
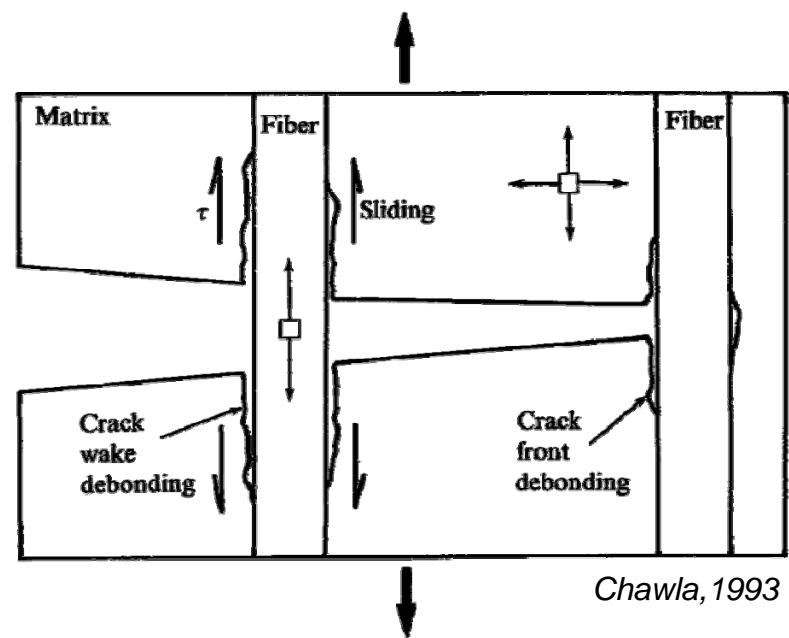
But can just get only limited improvement of tungsten toughness.

# $W_f/W$ composite concept

## Ideas from Ceramic Matrix Composites (CMC)

- Engineered fibre/matrix interfaces allow controlled crack deflection.
- Interfacial debonding and friction lead to internal energy dissipation.
- Higher strength is endowed by strong fibres.

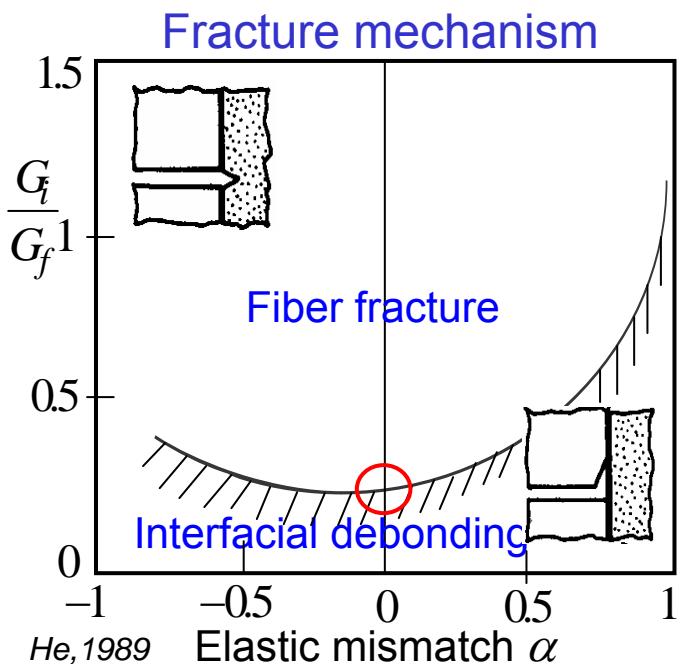
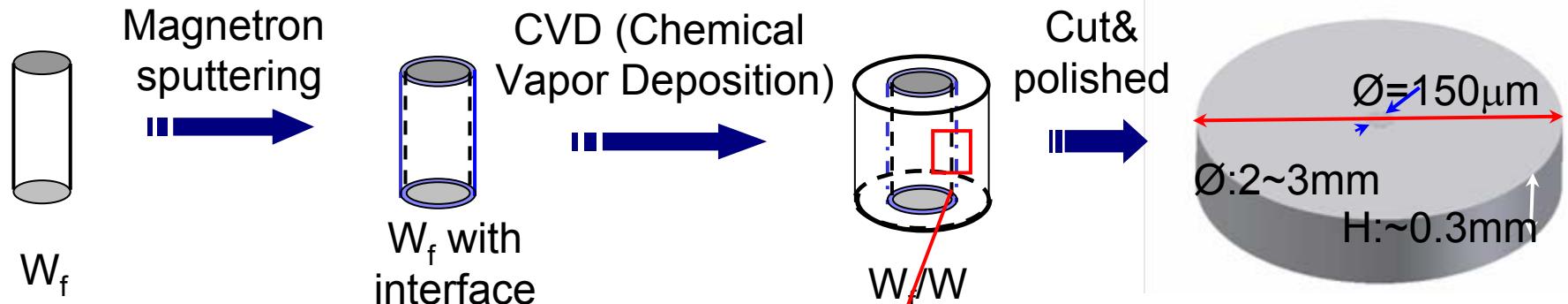
## CMC toughening mechanism (pseudo ductile)



Why not with tungsten?

Tungsten fiber reinforced Tungsten ( $W_f/W$ ):  
Chemical homogeneity.  
Appropriate coating will be applied for interface  
  
The aim of the present work is to explore the validity of the CMC toughening principle for the ( $W_f/W$ ) composite case.

# Specimen preparation



Debonding prerequisite

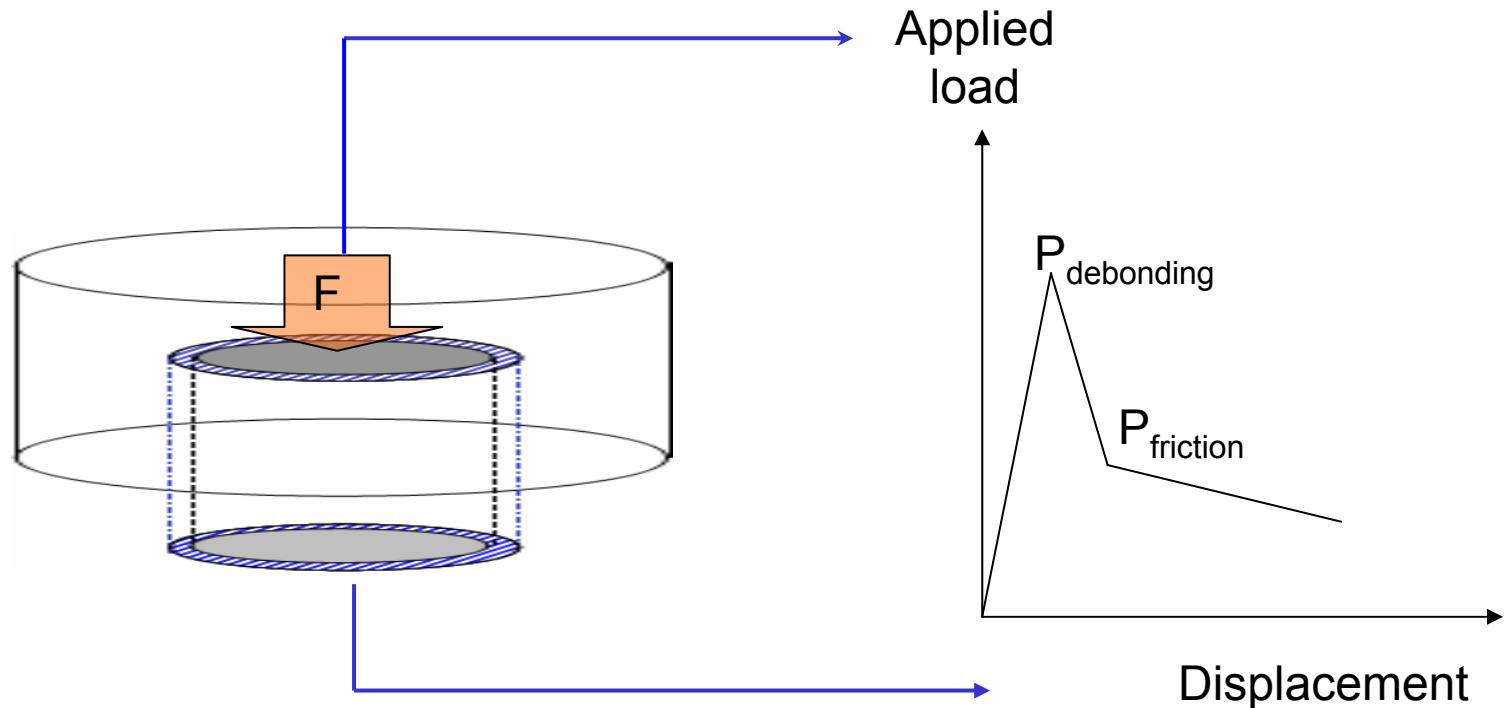
$\frac{\text{Interface fracture energy } G_i}{\text{Fiber fracture energy } G_f} \leq 0.25$

Interface	ZrO <sub>x</sub> single-layer	ZrO <sub>x</sub> /Zr multi-layer	Cu/W multi-layer	Cu single-layer
Thickness	266 nm	640 nm	900 nm	480 nm

How to identify the interfacial properties?

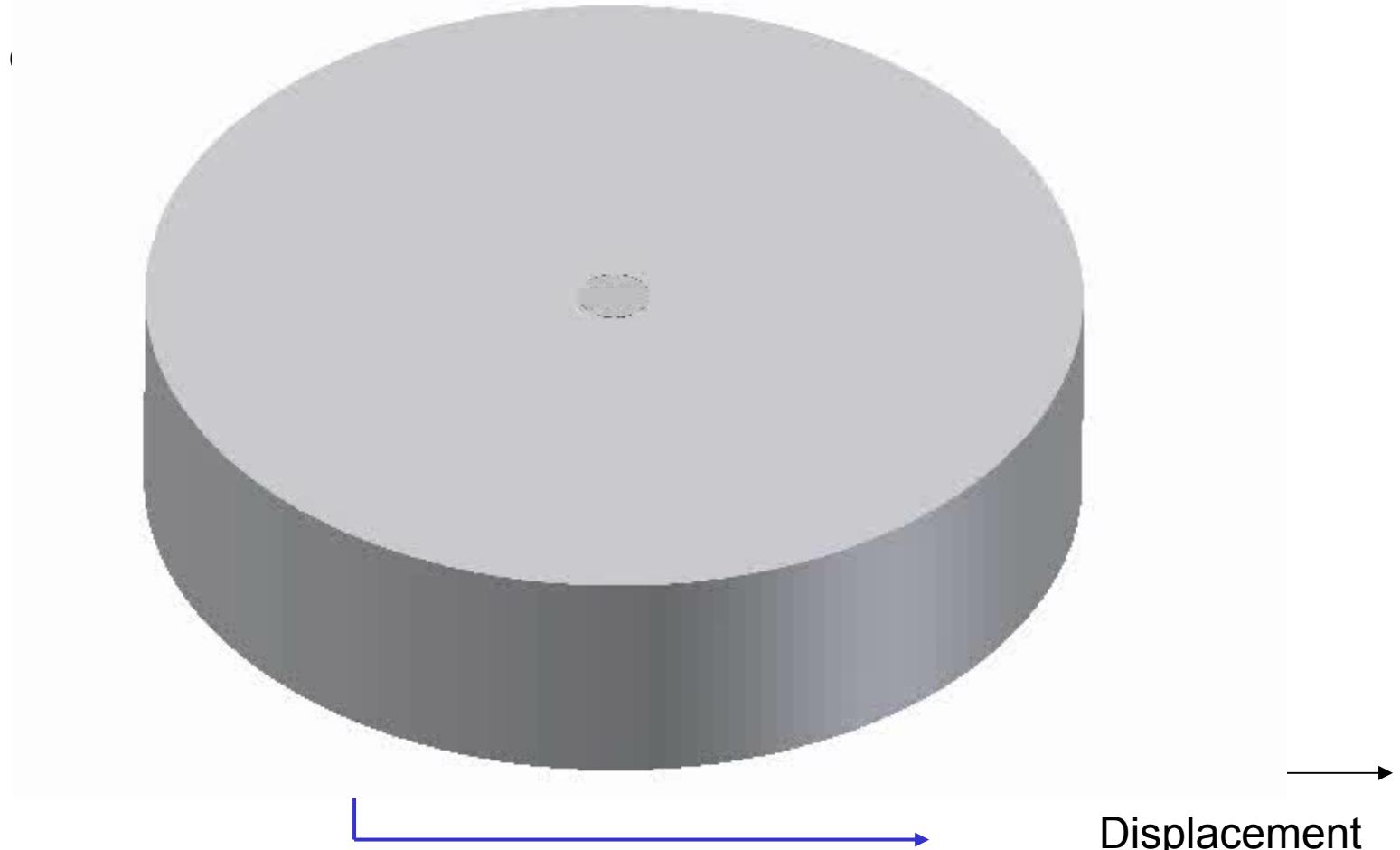
# Single fiber debonding — Push-out test

- Load is applied on the end of fiber, force and fiber movement are recorded.
- L-D curve reveals the debonding strength and frictional resistance.



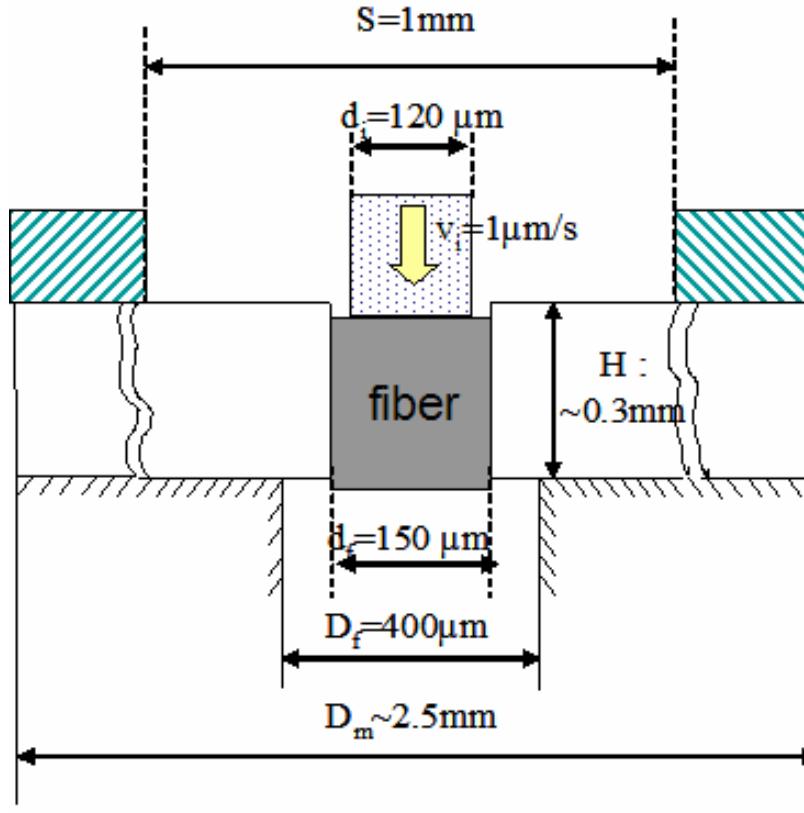
# Single fiber debonding — Push-out test

- Load
- L-D

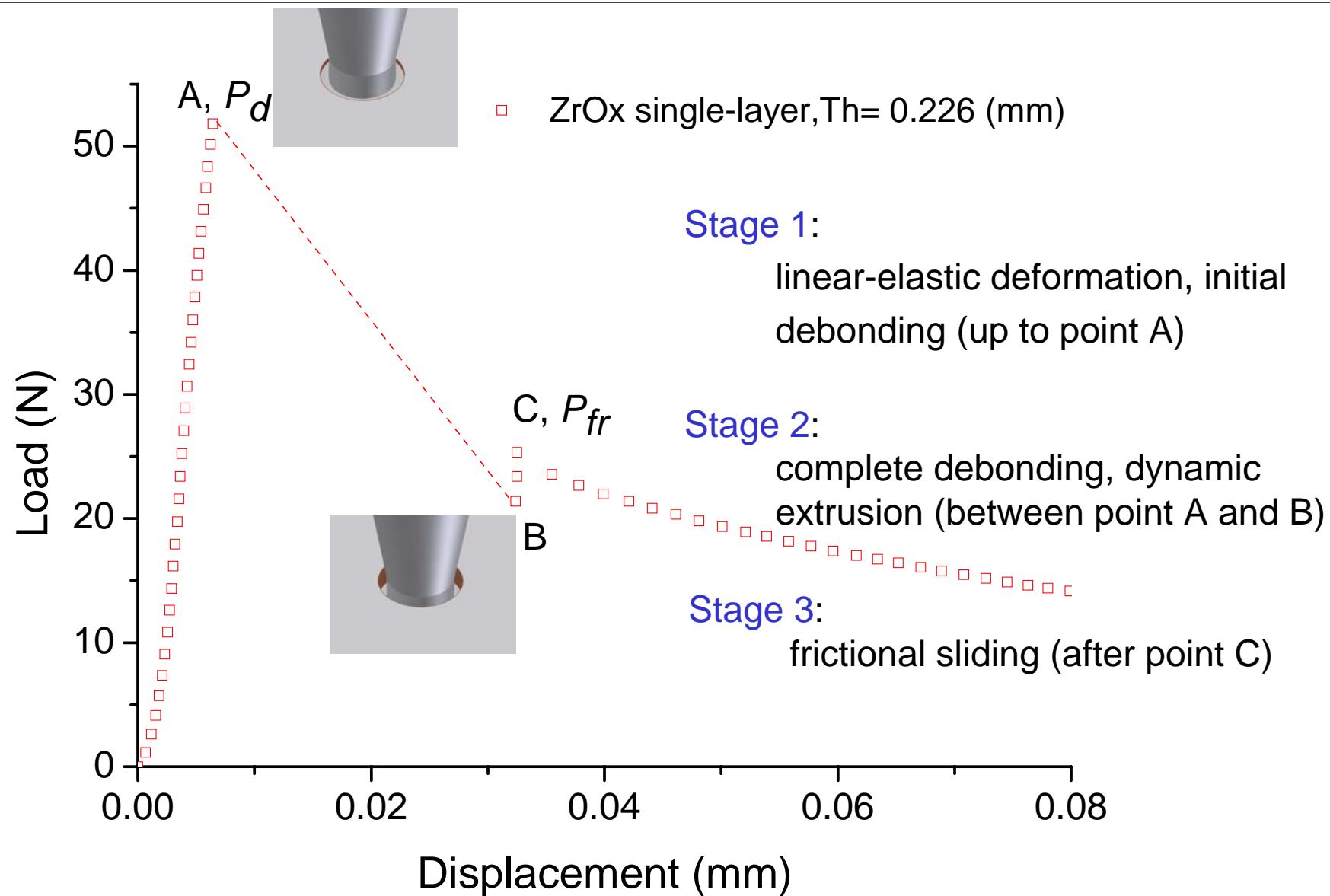


# Single fiber debonding — Push-out test

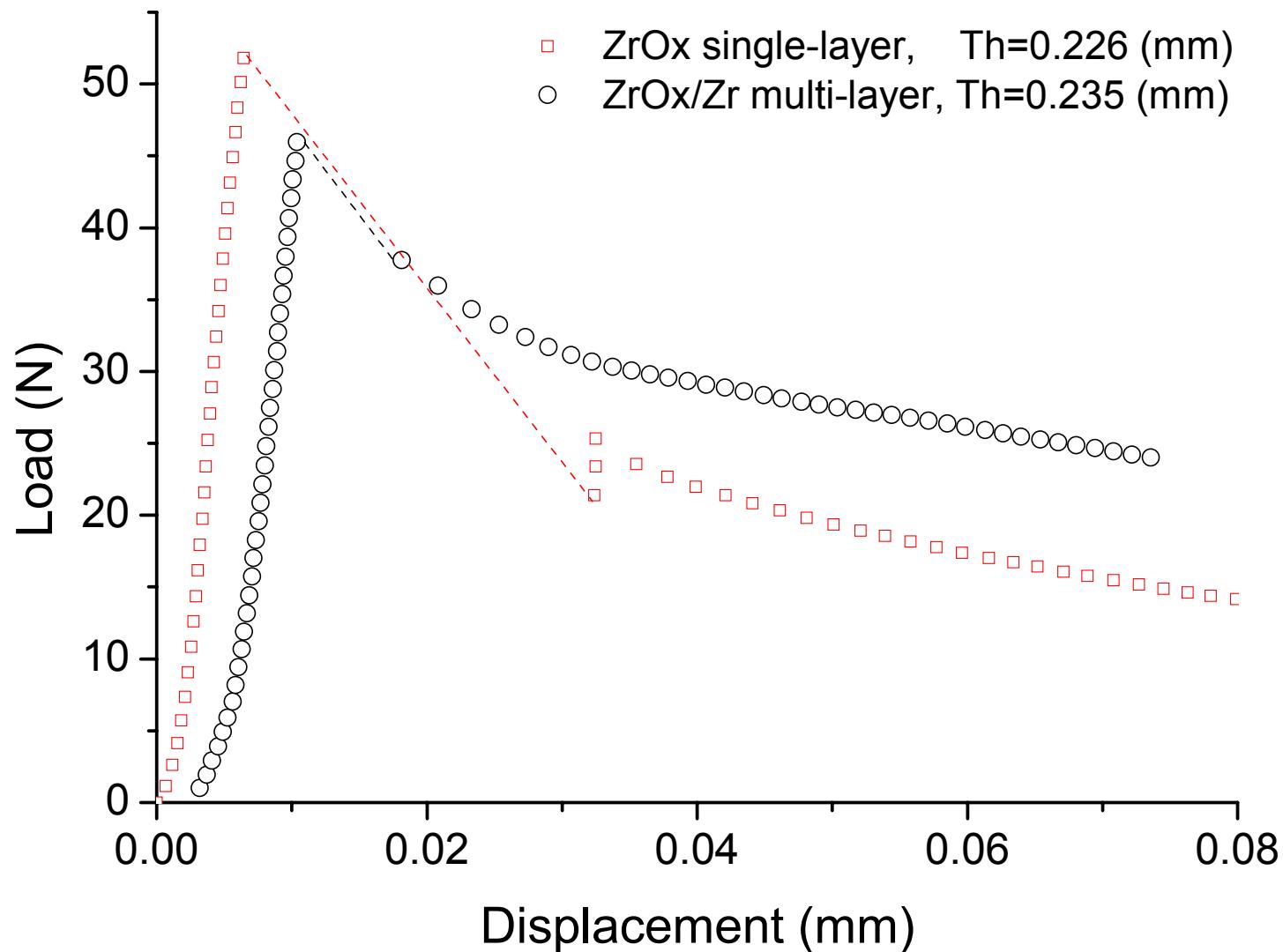
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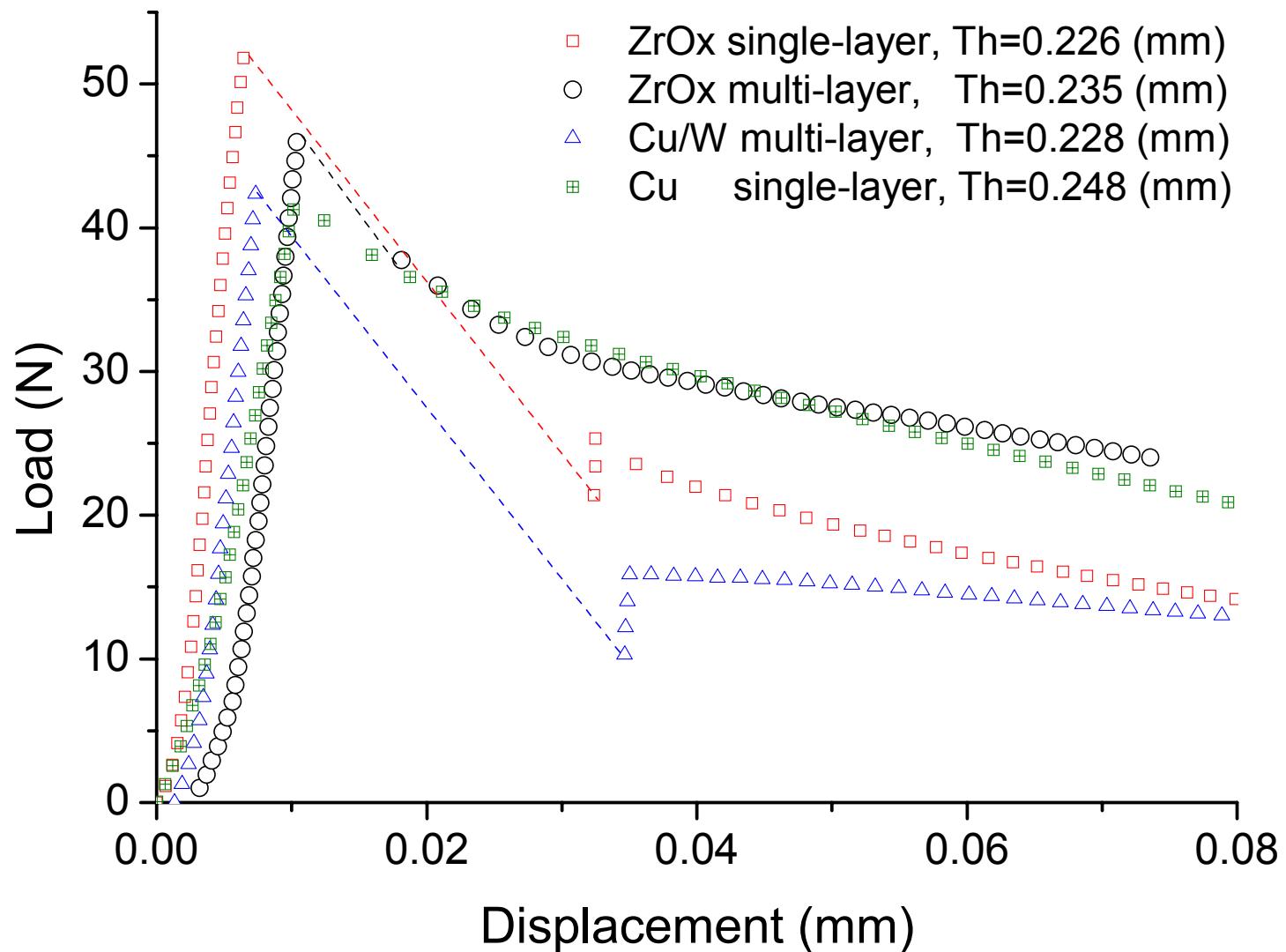
# Push-out curves



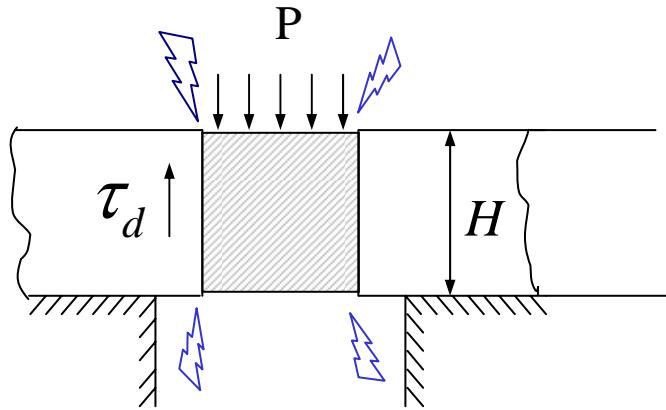
# Push-out curves



# Push-out curves



# Interfacial parameters calculation



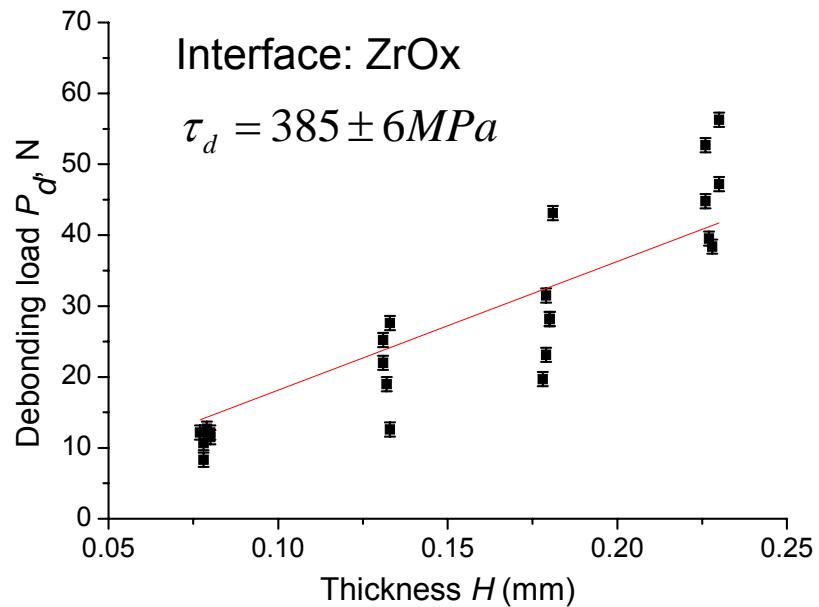
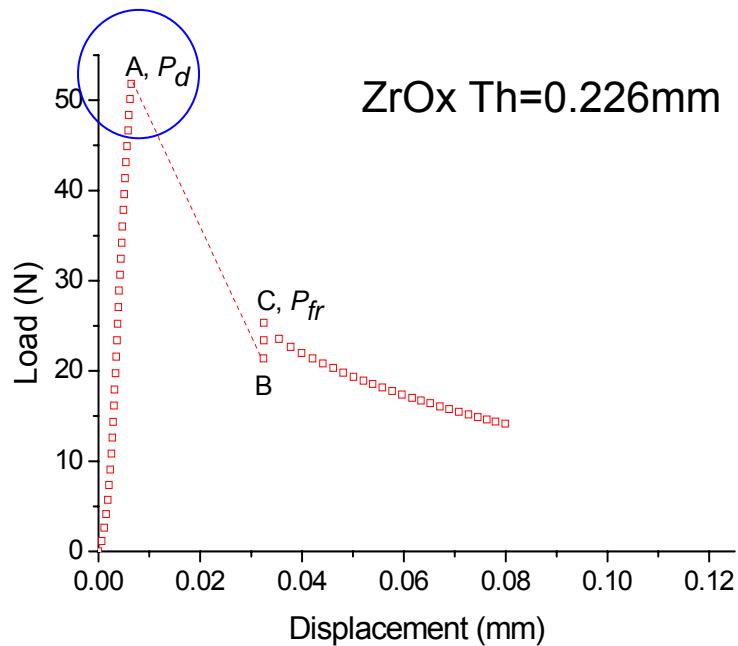
Interfacial shear strength,  $\tau_d$ :

maximum average shear stress the bonded interface can afford.

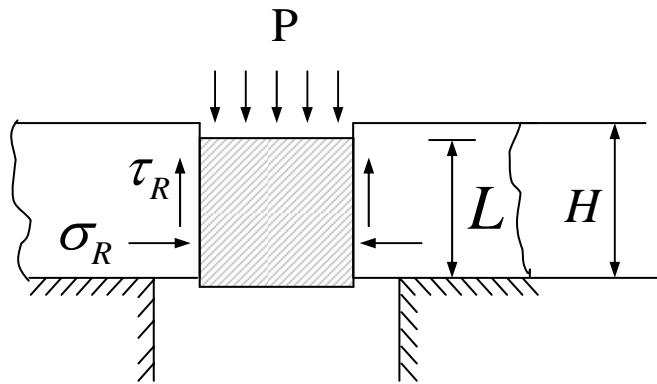
$$P_d = \frac{\pi d_f \tau_d}{\alpha} \tanh(\alpha H) \quad (\text{Lawrence 1970})$$

$P_d$ : debonding load;  $d_f$ : fiber diameter

$\alpha$ : shear-lag parameter;  $H$ : embedded length.



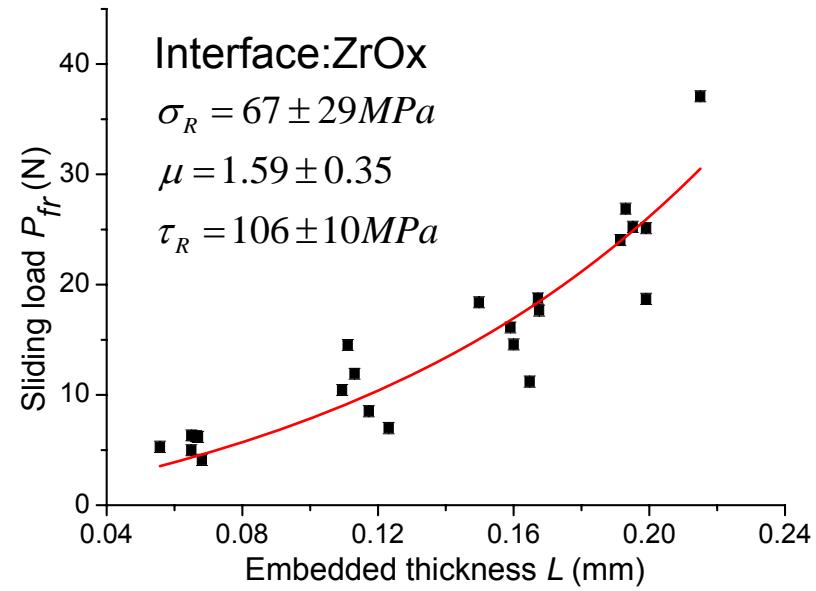
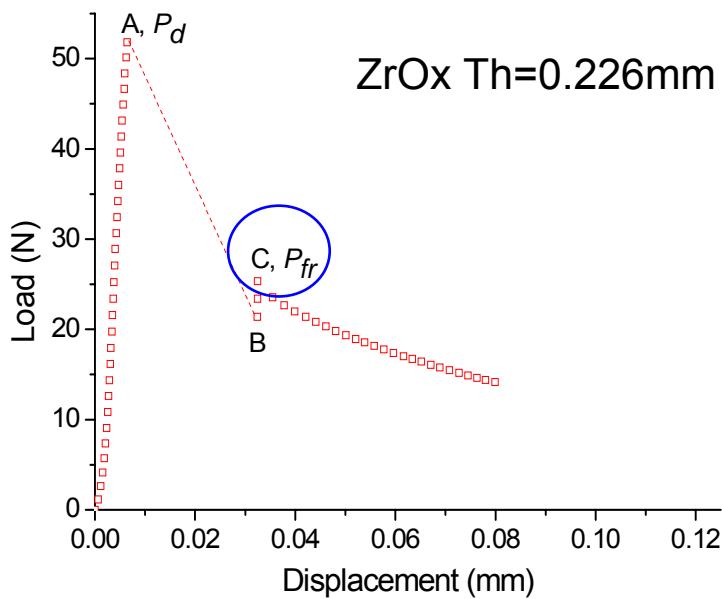
# Interfacial parameters calculation



**Roughness stress  $\sigma_R$** : radial stress due to mismatch of the surface asperity of a debonded interface; **Friction coefficient  $\mu$** :

$$P_{fr} = \frac{\pi r_f^2 \sigma_R}{k} \left[ \exp\left(\frac{2\mu k L}{r_f}\right) - 1 \right] \quad (\text{Shetty, 1988})$$

$P_{fr}$ : sliding load       $r_f$ : fiber diameter  
 $k$ : elastic parameter     $L$ : embedded length



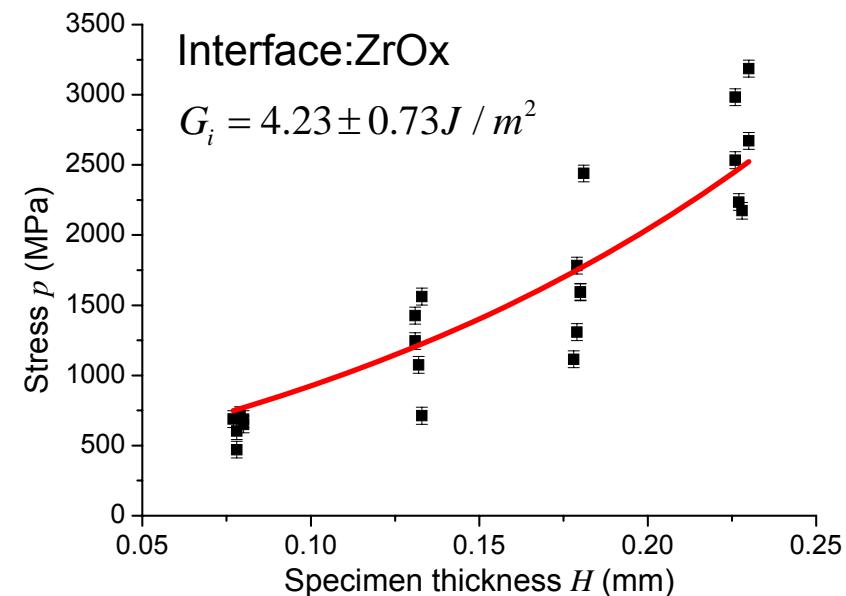
# Interfacial parameters calculation

Interfacial fracture toughness  $G_i$

$$\frac{\text{Interface fracture energy } G_i}{\text{Fiber fracture energy } G_f} \leq 0.25$$

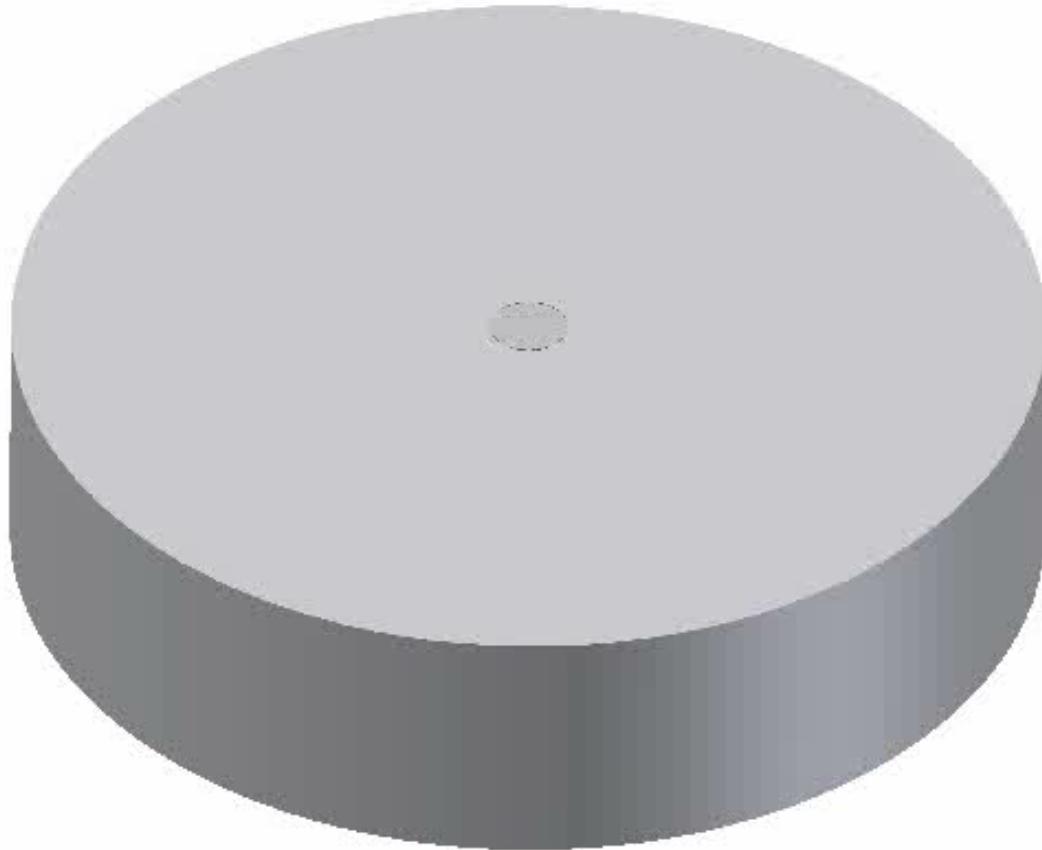
$$p = 2 \sqrt{\frac{G_i E_f}{B_2 R_f}} e^{\frac{2 \mu B_1 H}{R_f}} + \frac{\tau_0}{\mu B_1} (e^{\frac{2 \mu B_1 H}{R_f}} - 1) \quad (\text{Liang, 1993})$$

$$p = \frac{P_d}{\pi R_f^2} \quad H : \text{Specimen thickness}$$

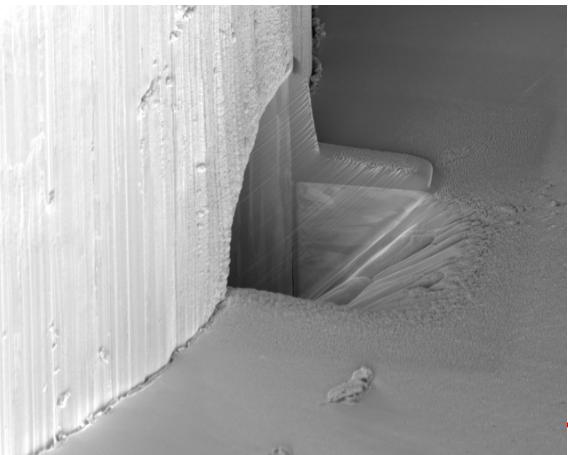


Interfaces	Debonding strength (MPa)	Asperity radial stress (MPa)	Friction coefficient, $\mu$	Fracture toughness, $\Gamma_i$ ( $\text{J} \cdot \text{m}^{-2}$ )	$\frac{G_i}{G_f}$ ( $G_f = 320 \text{ J} \cdot \text{m}^{-2}$ )
ZrO <sub>x</sub> Single-layer	$385 \pm 6$	$67 \pm 29$	$1.59 \pm 0.35$	$4.2 \pm 0.7$	0.013
Zr/ZrO <sub>x</sub> Multi-layer	$362 \pm 2$	$117 \pm 57$	$1.22 \pm 0.34$	$3.5 \pm 1.0$	0.011
W/Cu Multi-layer	$429 \pm 6$	$123 \pm 21$	$0.81 \pm 0.09$	$22.2 \pm 3.1$	0.068
Cu Single-layer	$393 \pm 4$	-	-	-	-

# Microstructure analysis



# Microstructure analysis



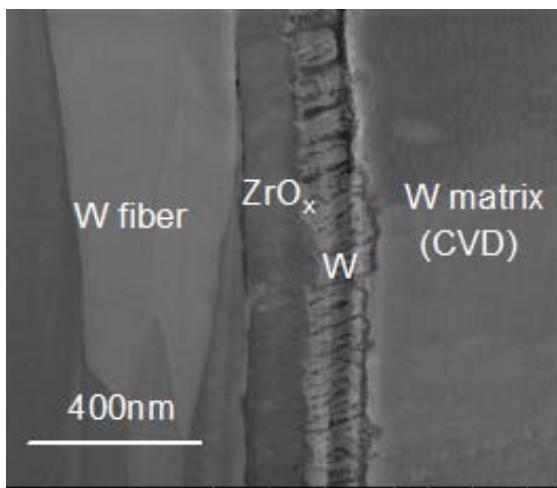
FIB cutting location

ZrO<sub>x</sub> mono-layer specimen:

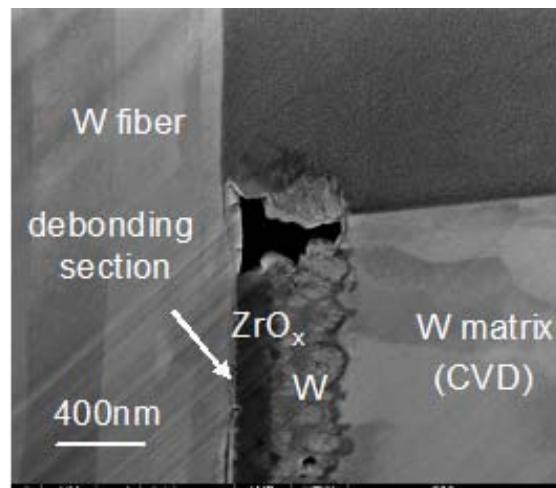
Debonding locations:

W fiber & ZrO<sub>x</sub> coating(MS)

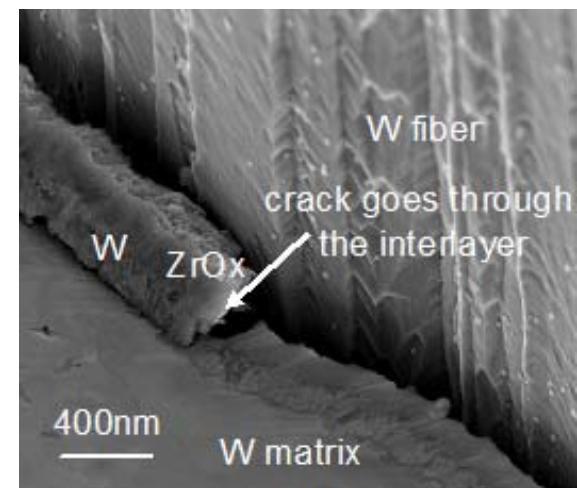
W coating(MS) & W matrix(CVD)



Before push-out

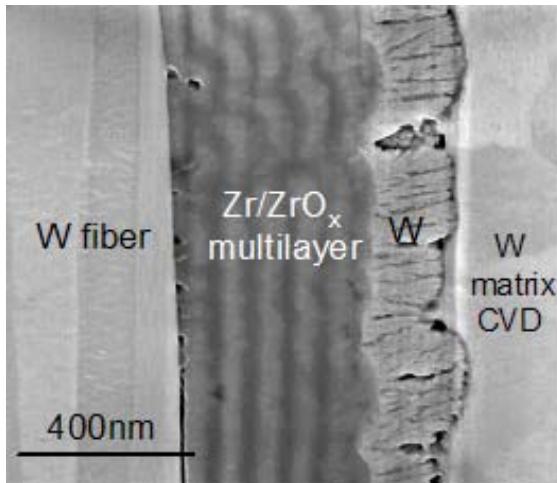


After push-out

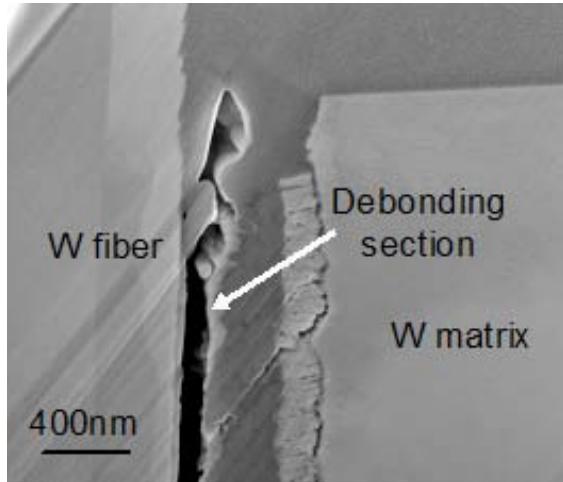


After push-out

# Microstructure analysis



Before push-out



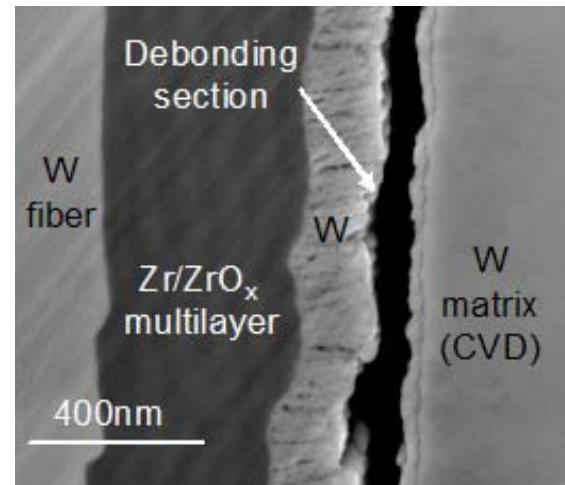
After push-out

ZrOx/Zr multi-layer specimen:

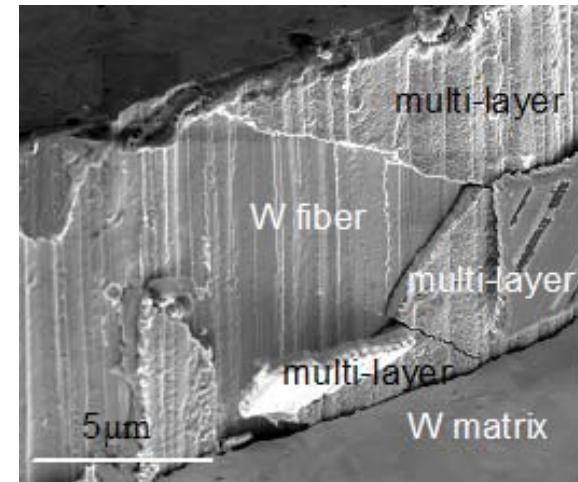
Debonding locations:

W fiber & ZrOx/Zr coating(MS)

W coating(MS) & W matrix(CVD)

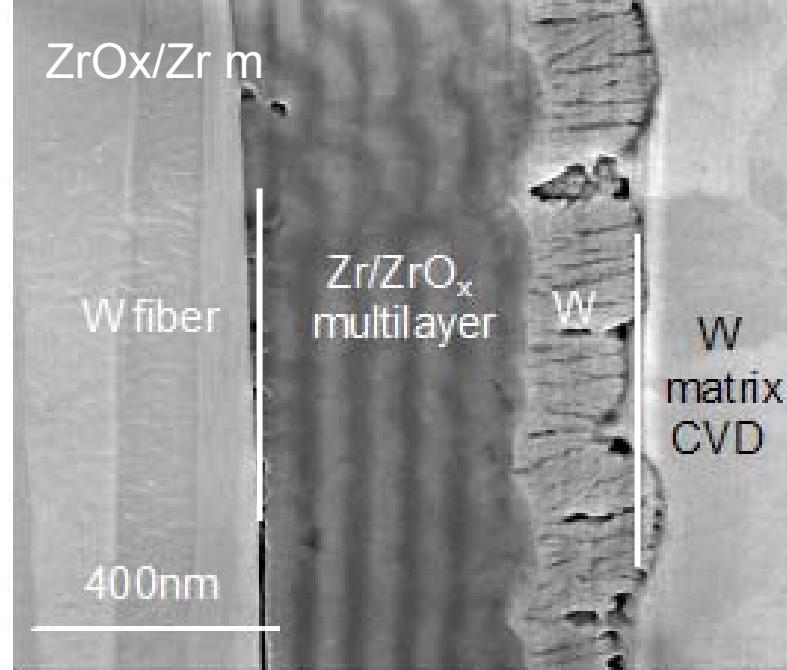
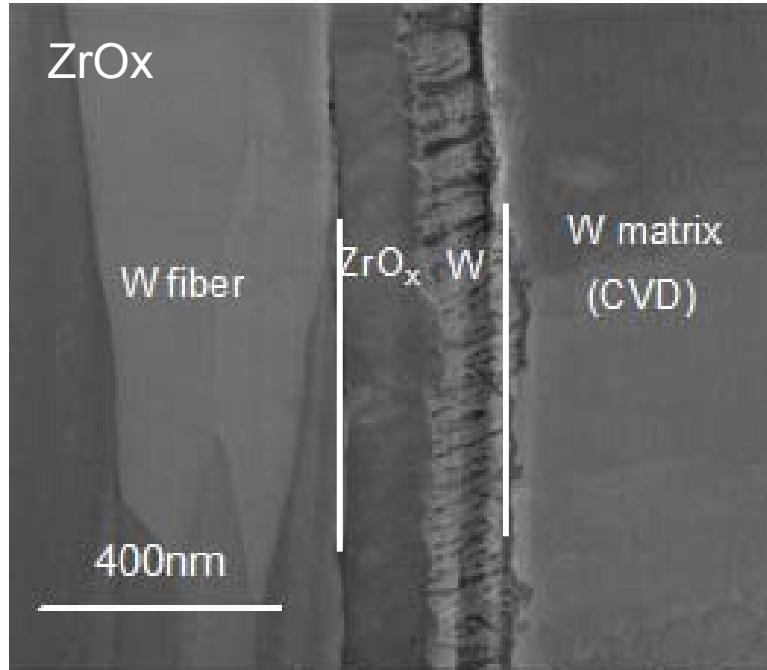


After push-out



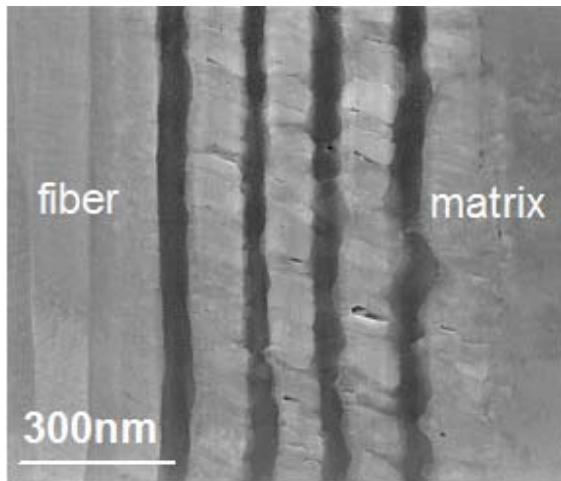
After push-out

# Microstructure analysis



Interfaces	Debonding strength (MPa)	Asperity radial stress (MPa)	Friction coefficient, $\mu$	Fracture toughness, $\Gamma_i$ ( $J^*m^{-2}$ )	$G_i/G_f$ ( $G_f = 320 J^*m^{-2}$ )
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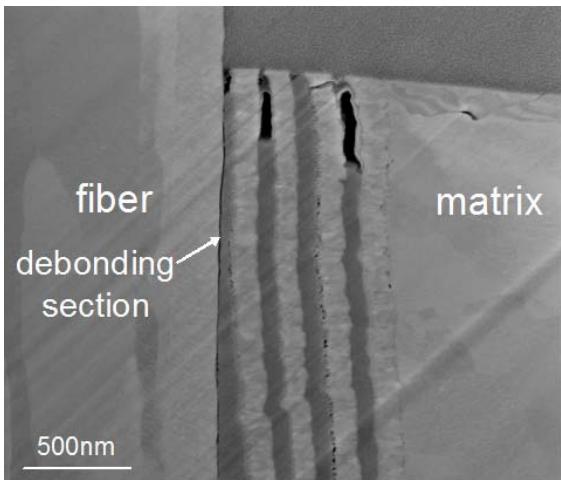
# Microstructure analysis



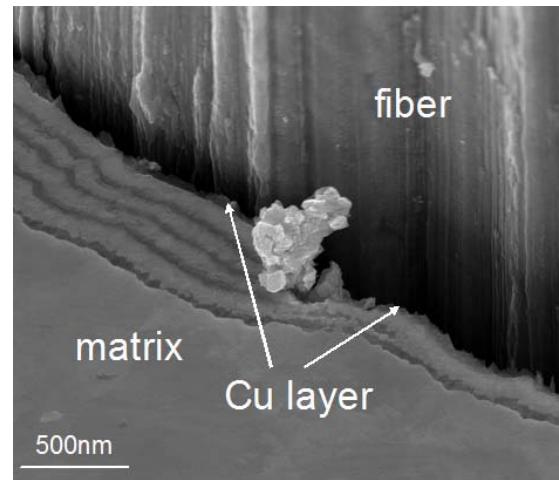
Before push-out

Cu/W multi-layer interface specimen:

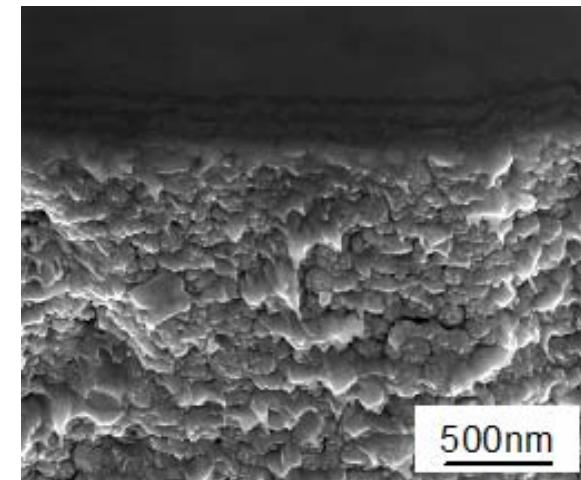
Debonding locations:  
One of the Cu layer



After push-out

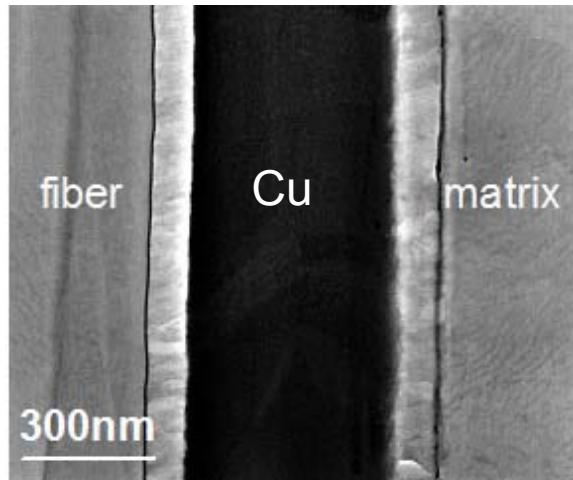


After push-out



After push-out

# Microstructure analysis

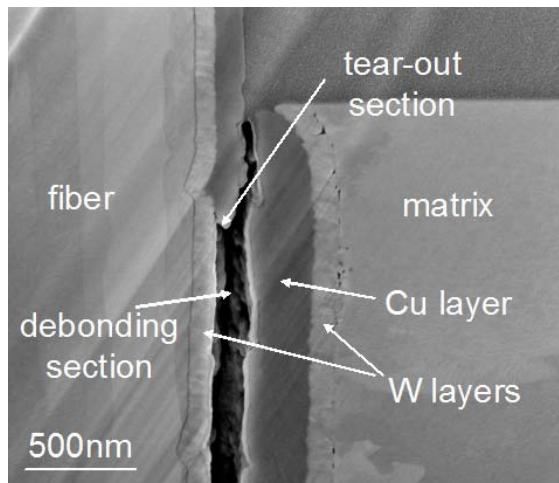


Before push-out

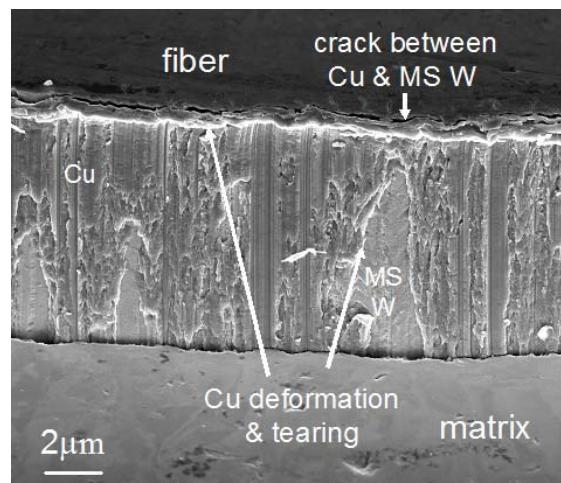
Cu single-layer interface specimen

Debonding locations:  
In interlayer

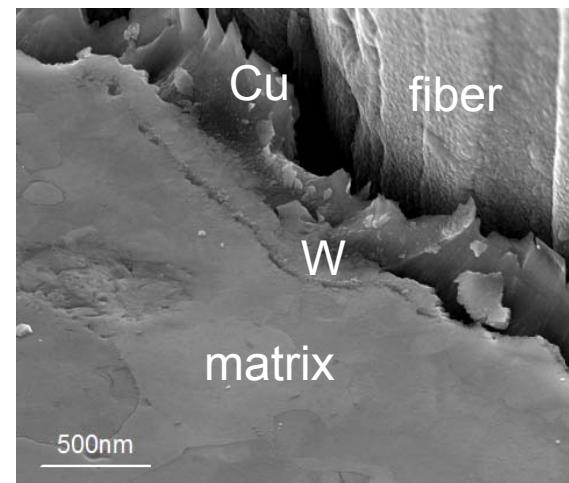
For Cu based specimens, debonding happened mainly in Cu layer



After push-out

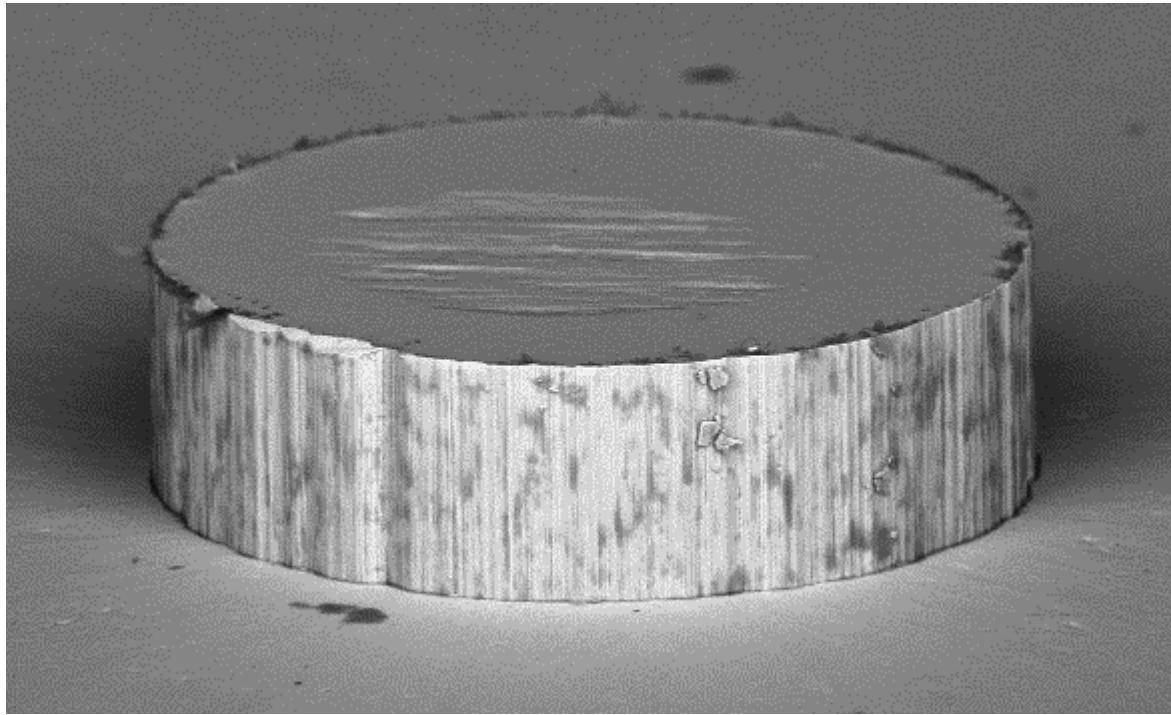


After push-out



After push-out

- A novel concept of  $W_f/W$  composite was developed according to CMC mechanism.
- Different fiber/matrix interfaces were investigated by means of fiber push-out test.
- The estimated fracture energy values satisfied the crack deflection criterion so that interface debonding is preferred than fiber fracture.
- Microstructure investigation results also support the calculated values.



**Thanks for your attention !**